

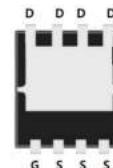


Features

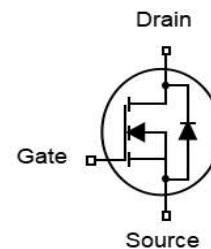
- N-Channel
- Excellent gate charge x $R_{DS(on)}$ product
- Very low on-resistance $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating
- 100% EAS Tested

V_{DS}	60	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	2.4	mΩ
I_D	160	A

DFN5x6



Part ID	Package Type	Marking	Packing
ZTG020N06G	DFN5x6	ZTG020N06G	5000pcs/Reel



Absolute Maximum Ratings $T_A=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
I_{DM}	Drain Current-Continuous@ Current-Pulsed	$T_c=25^\circ\text{C}$	640	A
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous	$T_c=25^\circ\text{C}$	160	A
		$T_c=100^\circ\text{C}$	102	A
P_D	Maximum Power Dissipation	125	W	
dv/dt	Drain Source voltage slope, $V_{DS} \leq 48$ V	50	V/ns	
dv/dt	Reverse diode dv/dt , $V_{DS} \leq 48$ V, $I_{SD} < I_D$	15	V/ns	
$R_{\theta JC}$	Thermal Resistance-Junction to Case (Note 2)	1.15	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 5)	232	mJ	



Electrical Characteristics ($T_j=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60	--	--	V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.3	3.0	3.7	V
RDS(on)	Drain-Source On-State Resistance ^(Note 3)	$V_{GS}=10\text{V}, I_D=50\text{A}$	--	2.4	3.0	$\text{m}\Omega$

Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated) ^(Note 4)

Ciss	Input Capacitance	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	4100	--	pF
Coss	Output Capacitance		--	1010	--	pF
Crss	Reverse Transfer Capacitance		--	36	--	pF
Rg	Gate Resistance	f=1MHz	--	3.4	--	Ω
Qg	Total Gate Charge	$V_{DS}=30\text{V}, I_D=80\text{A}, V_{GS}=10\text{V}$	--	62	--	nC
Qgs	Gate-Source Charge		--	25	--	nC
Qgd	Gate-Drain Charge		--	14	--	nC

Switching Characteristics ^(Note 4)

Td(on)	Turn-on Delay Time	$V_{DD}=30\text{V}, I_D=80\text{A}, R_G=3.0\Omega, V_{GS}=10\text{V}$	--	22	--	ns
Tr	Turn-on Rise Time		--	31	--	ns
Td(off)	Turn-Off Delay Time		--	47	--	ns
Tf	Turn-Off Fall Time		--	19	--	ns

Source-Drain Diode Characteristics@ $T_j = 25^\circ\text{C}$ (unless otherwise stated)

Is	Diode Forward Current ^(Note 2)		--	--	160	A
VSD	Forward on voltage ^(Note 3)	$I_S=80\text{A}, V_{GS}=0\text{V}$	--	--	1.4	V
Tr	Reverse Recovery Time	$V_{DD}=30\text{V}, I_F=80\text{A}$ $di/dt=100\text{A}/\mu\text{s}$	--	50	--	ns
Qrr	Reverse Recovery Charge		--	66	--	nC

Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, $t \leq 10$ sec.
- Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- Guaranteed by design, not subject to production
- EAS condition : $T_j=25^\circ\text{C}, V_{DD}=50\text{V}, V_G=10\text{V}, L=0.1\text{mH}, R_g=25\Omega$



Typical Electrical and Thermal Characteristics

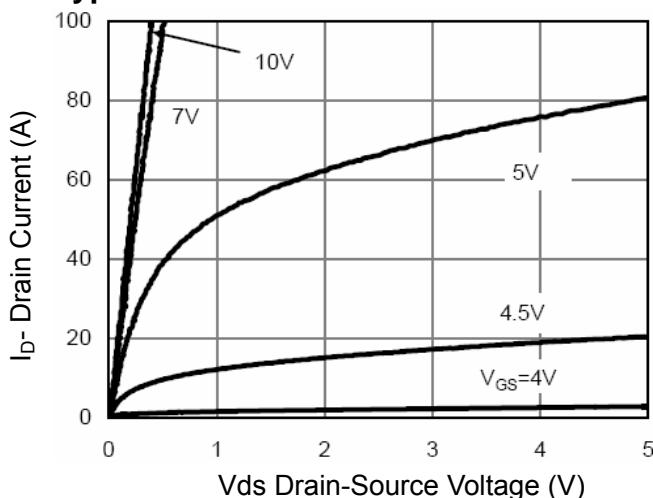


Figure 1 Output Characteristics

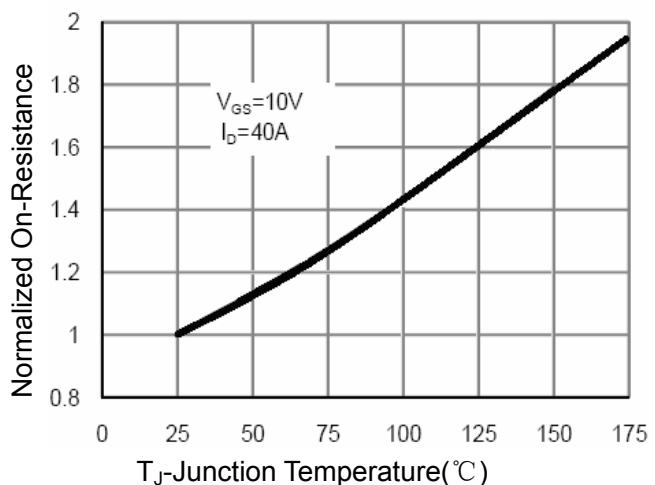


Figure 4 Rdson-Junction Temperature

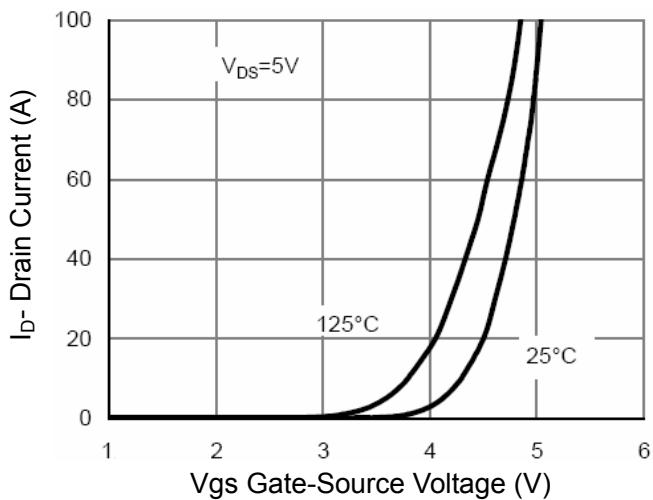


Figure 2 Transfer Characteristics

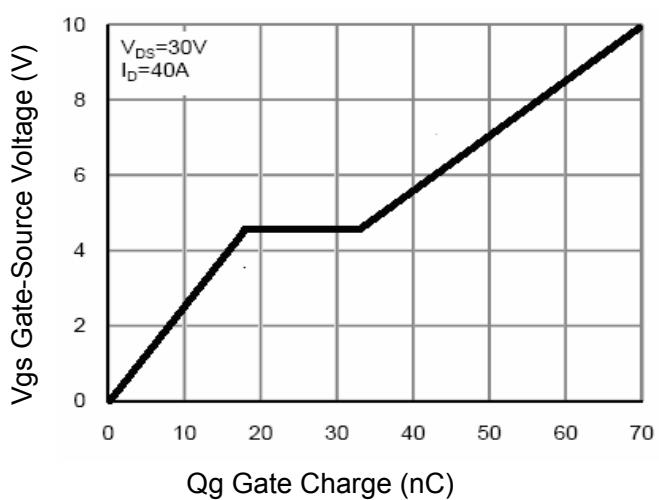


Figure 5 Gate Charge

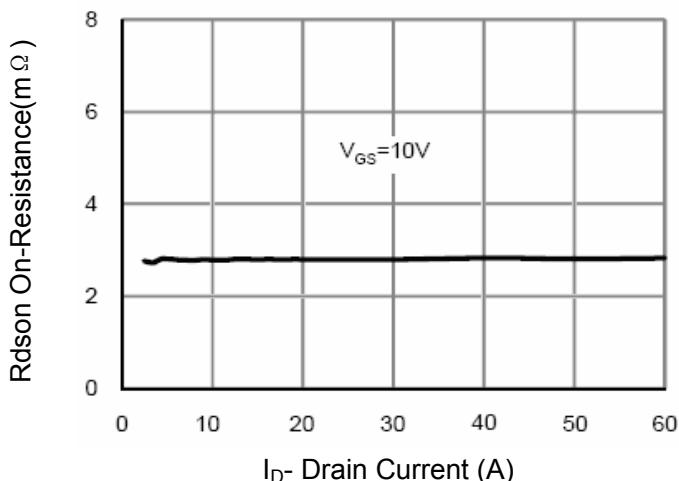


Figure 3 Rdson- Drain Current

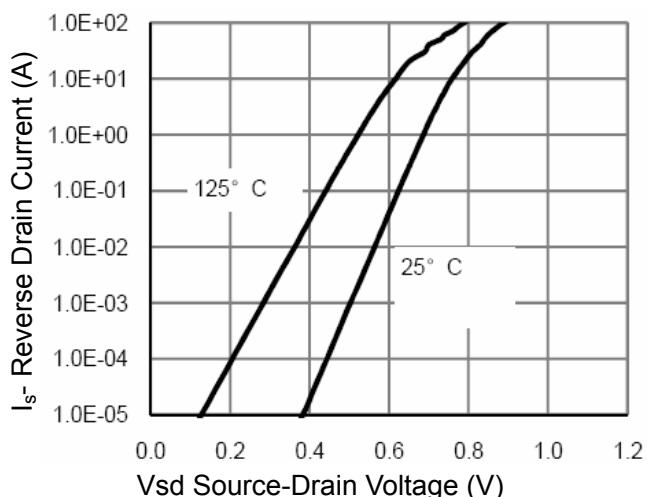


Figure 6 Source- Drain Diode Forward

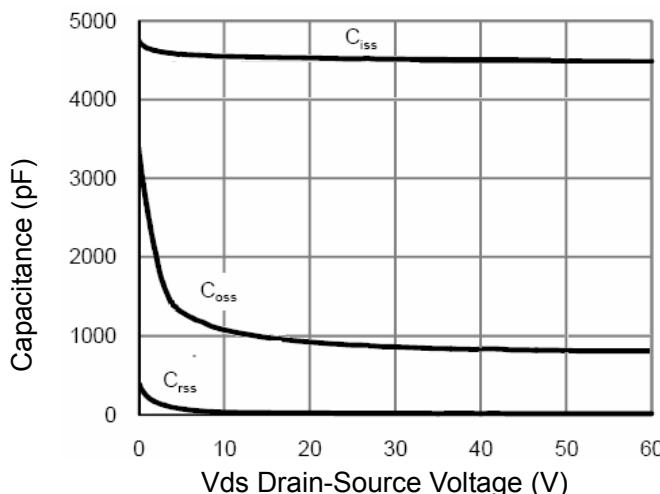


Figure 7 Capacitance vs Vds

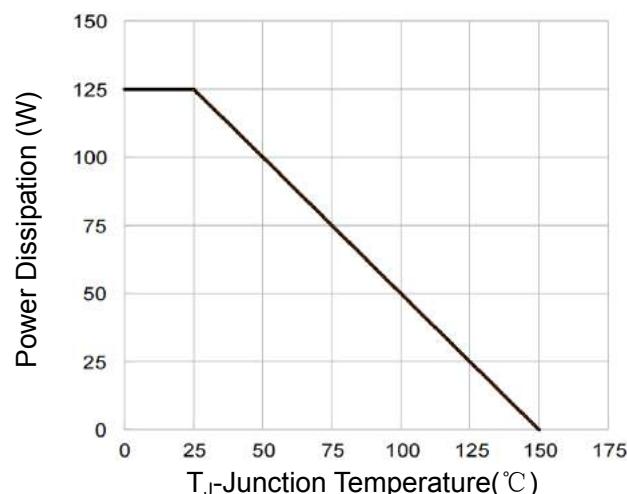


Figure 9 Power De-rating

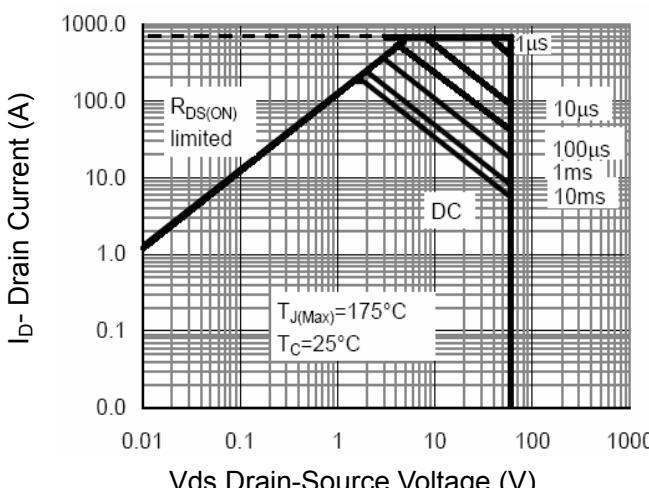


Figure 8 Safe Operation Area

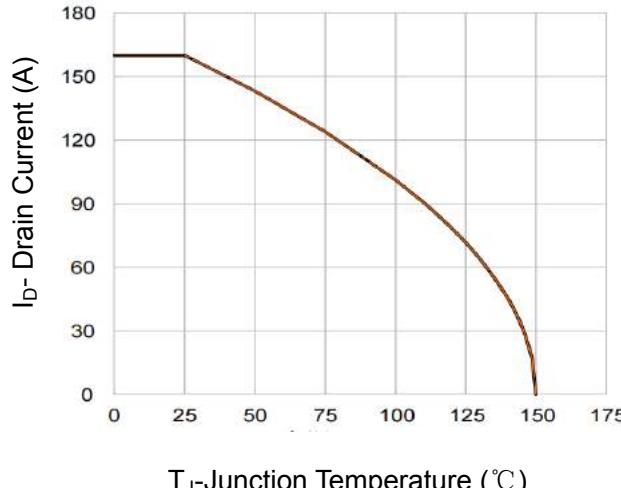


Figure 10 Current De-rating

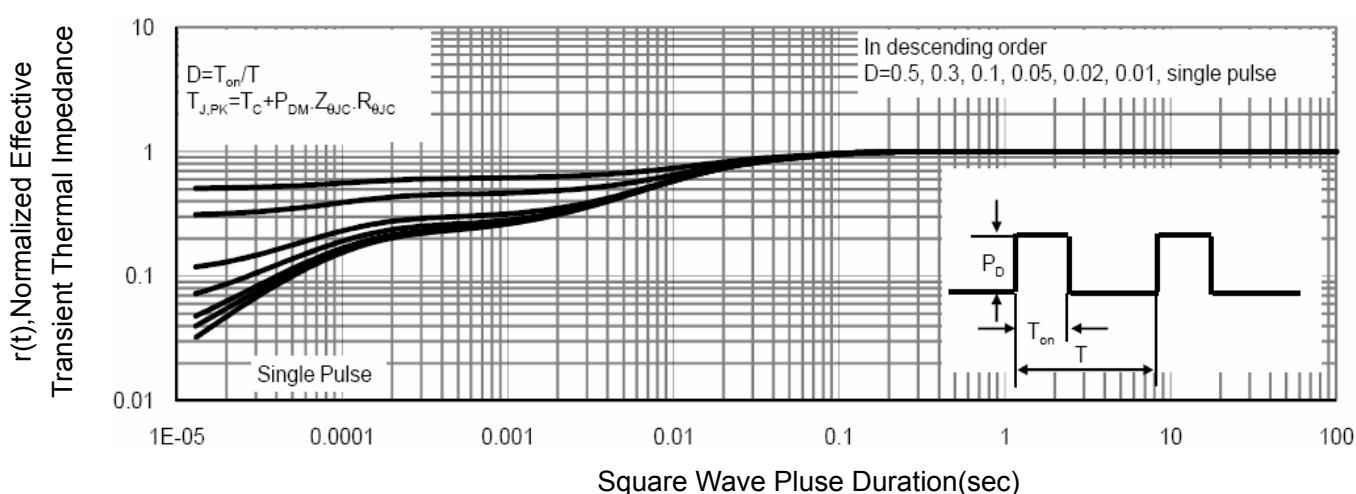
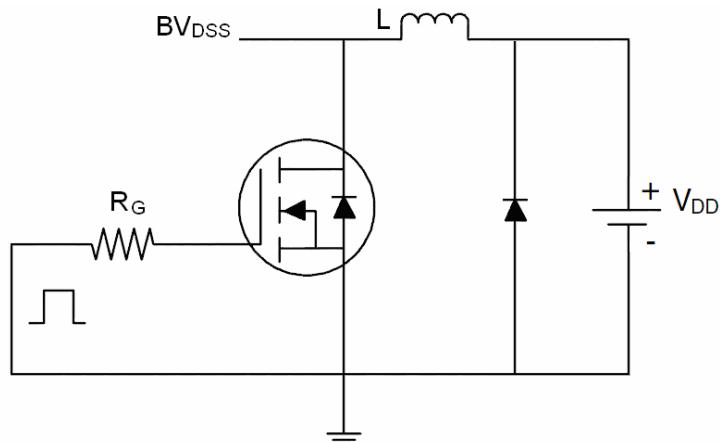


Figure 11 Normalized Maximum Transient Thermal Impedance

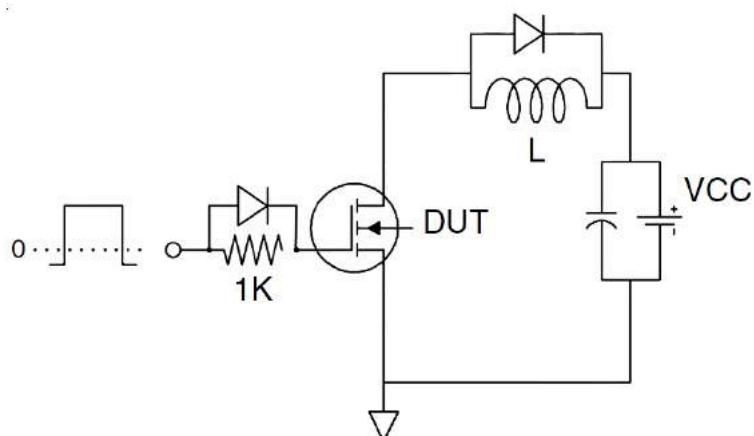


Test Circuit

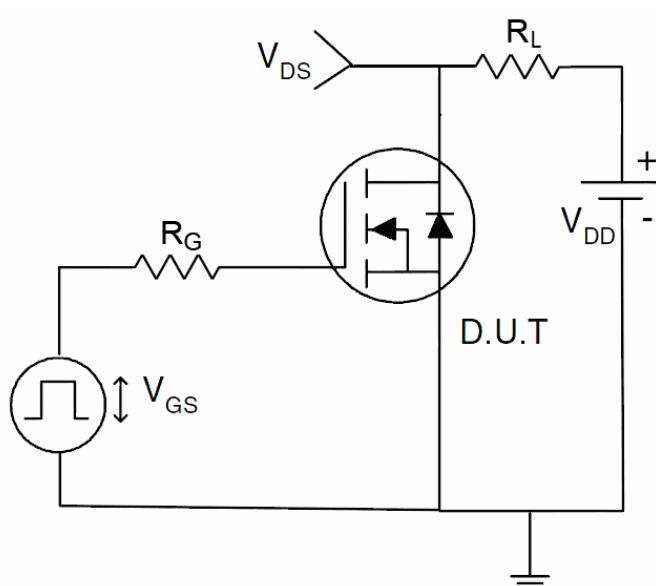
1) E_{AS} test Circuit



2) Gate charge test Circuit

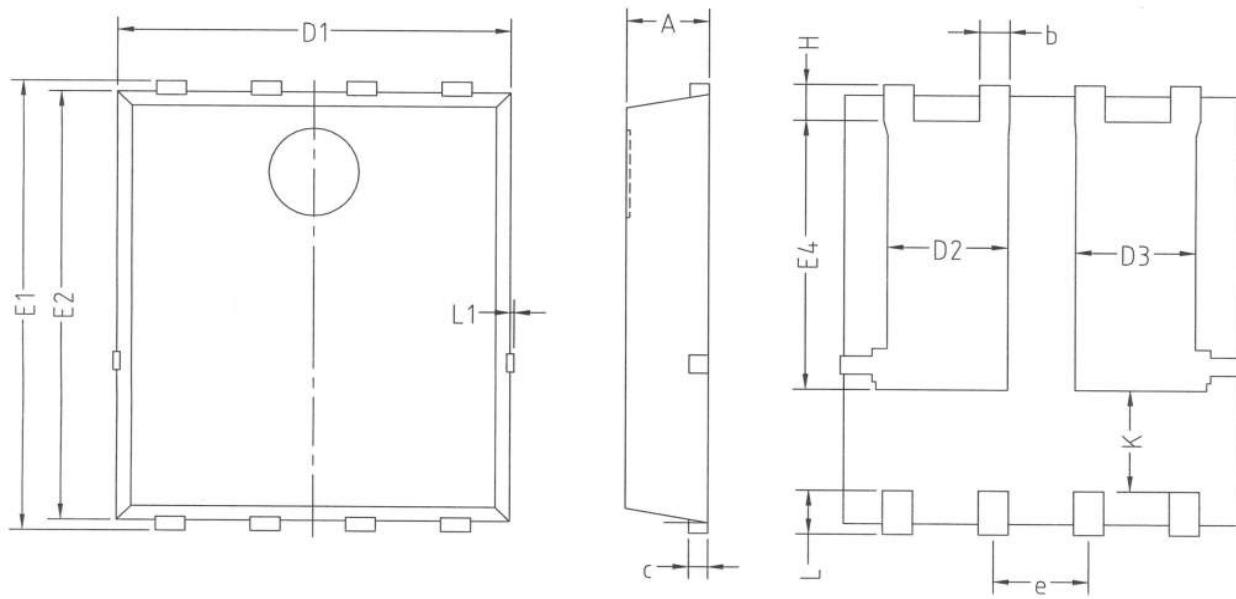


3) Switch Time Test Circuit





DFN5x6-8L Package Information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.154	0.254	0.354
D1	5.00	5.20	5.40
D2	1.40	1.60	1.80
D3	1.40	1.60	1.80
e	1.27BSC		
E1	5.95	6.15	6.35
E2	5.66	5.86	6.06
E4	3.47	3.67	3.87
H	0.40	0.50	0.60
K	1.23	1.38	1.53
L	0.30	0.60	0.70
L1			0.12

Customer Service

Sales and Service:

zj@ztasemi.com